

NCD8A65F

SILICON CARBIDE SCHOTTKY DIODE



VOLTAGE: 650 Volts

CURRENT: 8 Amperes

Package: TO-220F-2L

Marking And Polarity

FEATURES

- Extremely Low Reverse Current
- Zero Reverse Recovery Current
- Positive Temperature Coefficient on VF
- Temperature-Independent Switching Behavior
- Low Capacitive Charge

DESCRIPTION

Nihang provides leading edge technology for the SiC Schottky barrier diodes with the advanced thin-wafer technology. The new family of products showing improved efficiency over all load conditions, attributed to its lower figure of merit ($Q_c \times V_F$).

TYPICAL APPLICATIONS

- Switch Mode Power Supplies (SMPS)
- Power Factor Correction or DC/DC Stages
- Free Wheeling Diodes in Inverter Stages
- AC/DC Converters
- Uninterruptible Power Supplies

Remark:

- NH=nihang trademark
- FF=Product line code, According to actual changes
YWW=Date code, According to actual changes
EDDKF=Internal code, According to actual changes
- NCD8A65F=Model

Maximum Ratings (Ta=25°C Unless otherwise specified)

Parameter	Test Conditions	Symbol	NCD8A65F	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	650	V
Maximum DC Blocking Voltage		V_{DC}	650	V
Maximum Average Forward Rectified Current	@TC= 25 °C	$I_{F(AV)}$	21	A
	@TC= 150 °C		8	
Peak Forward Surge Current	8.3ms Single Half Sine-wave Superimposed On Rate Load	I_{FSM}	33	A
Current Squared Time Per Diode	t<8.3ms	I^2t	4.5	A ² sec
Power Dissipation	@TC= 25 °C	P_{tot}	54	W
	@TC= 110 °C		23	

Electrical Characteristics (Ta=25°C Unless otherwise specified)

Parameter	Test Conditions		Symbol	NCD8A65F			Unit
				Min.	Typ.	Max.	
Instaneous forward voltage per diode (note1)	Ta=25°C	$I_F = 8 A$	V_F	--	1.60	1.90	V
	Ta=175°C			--	2.00	2.30	
Maximum DC Reverse Current at Rated DC Blocking Voltage	Ta=25°C	$V_R = V_{RRM}$	I_{RRM}	--	1	10	uA
	Ta=175°C	$V_R = V_{RRM}$		--	10	50	
Total Capacitive Charge	VR= 400 V, TJ= 25°C $Q_c = \int_0^{VR} C(V) \cdot DV$		Q_c	--	15.0	--	nC
Total Capacitance	1 V, 1MHz		C	--	268	--	pF
	300 V, 1MHz			--	30	--	
	600 V, 1MHz			--	23	--	
Capacitance Stored Energy	VR= 400 V		E_c	--	2	--	uJ

Thermal Characteristics (Ta=25°C Unless otherwise specified)

Parameter	Symbol	NCD8A65F	Unit
Operating Junction Temperature Range	T_J	-55 to 175	°C
Storage Temperature Range	T_{STD}	-55 to 175	
Typical thermal resistance	$R_{\theta JC}$	2.8	°C/W

NCD8A65F

SILICON CARBIDE SCHOTTKY DIODE



Typical Characteristics Curves

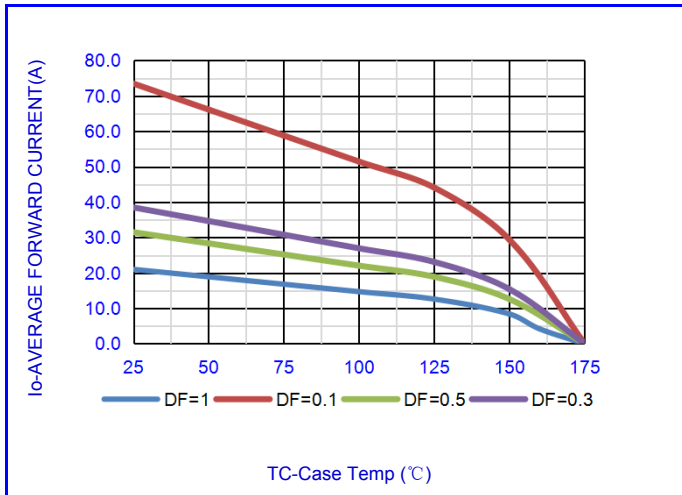


Fig.1-FORWARD CURRENT DERATING CURVE

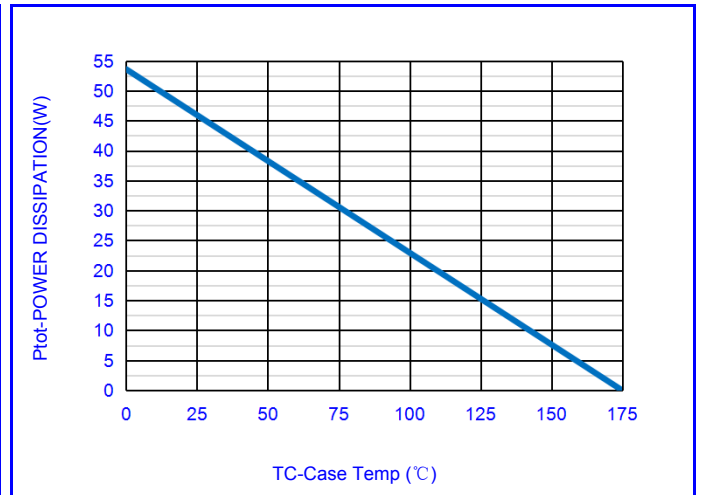


Fig.2-POWER DERATING CURVE

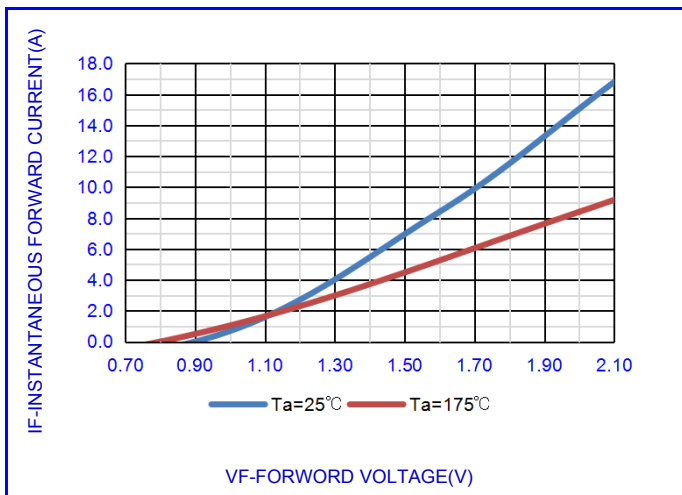


Fig.3- TYPICAL INSTANTANEOUS FORWARD

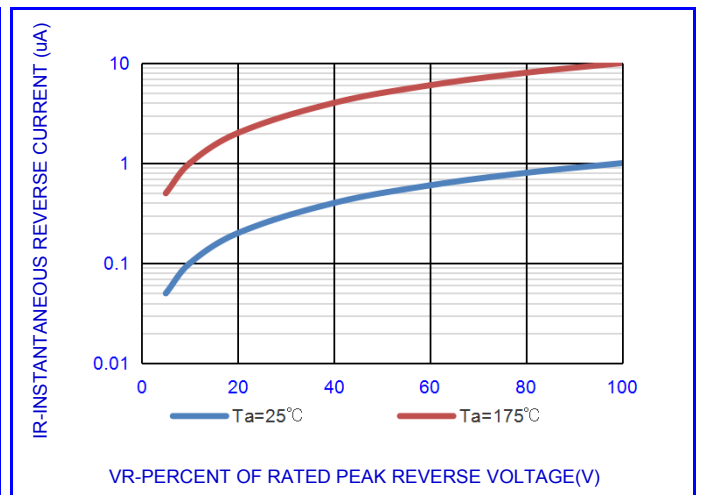


Fig.4- TYPICAL REVERSE CHARACTERISTICS

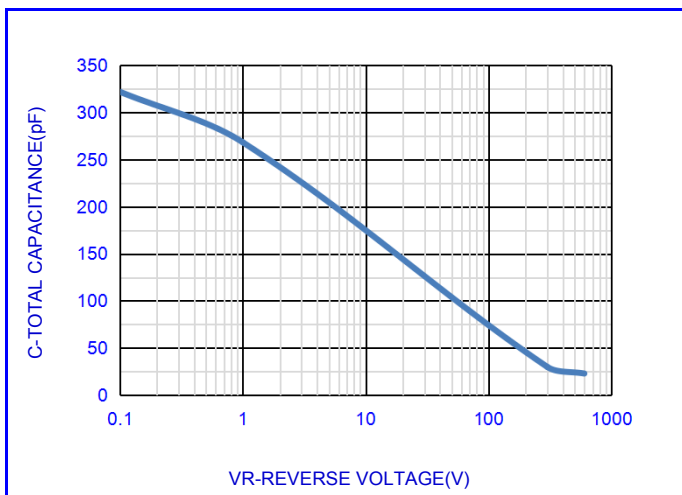


Fig.6-TOTAL CAPACITIVE CHARGE vs. REVERSE VOLTAGE

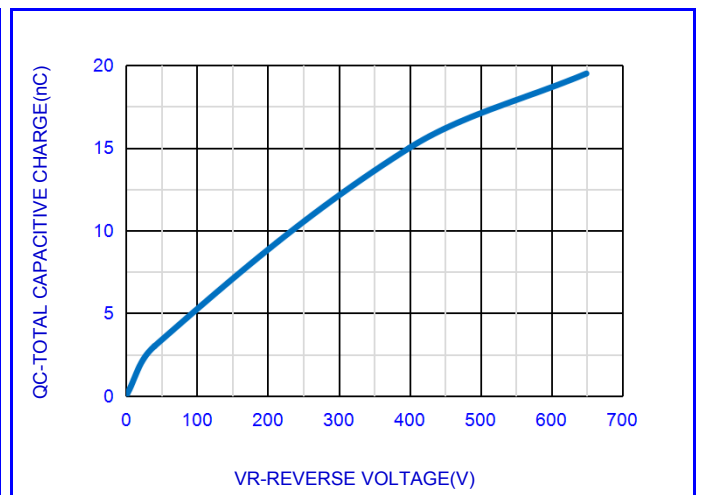


Fig.6-TOTAL CAPACITIVE CHARGE vs. REVERSE VOLTAGE

NCD8A65F

SILICON CARBIDE SCHOTTKY DIODE



Typical Characteristics Curves

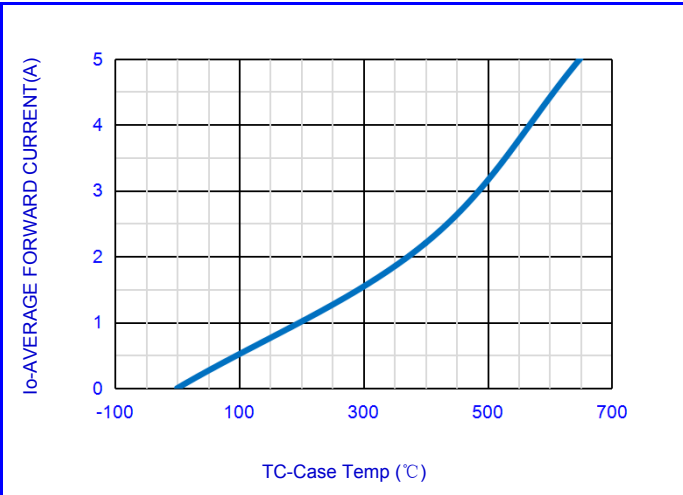


Fig.7-CAPACITANCE STORED ENERGY vs. REVERSE VOLTAGE

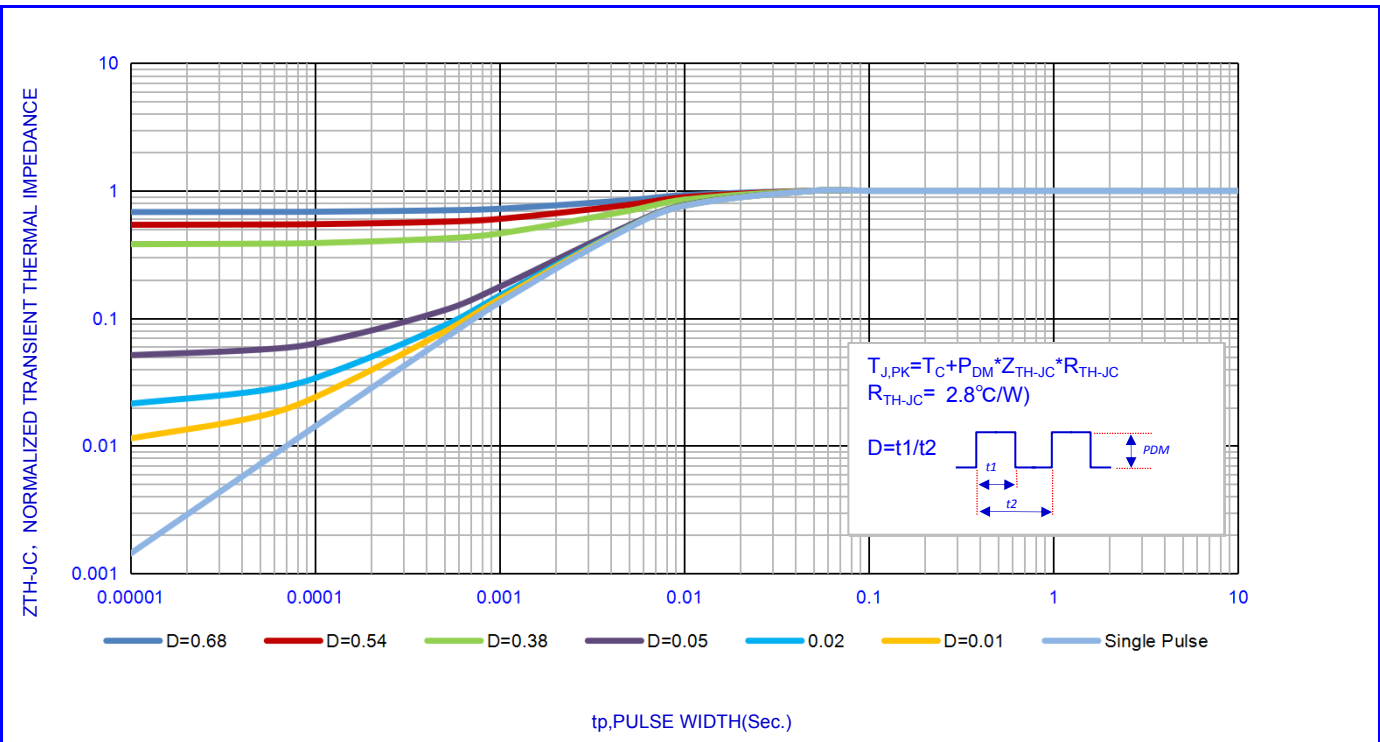


Fig.8- NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE vs.PULSE WIDTH

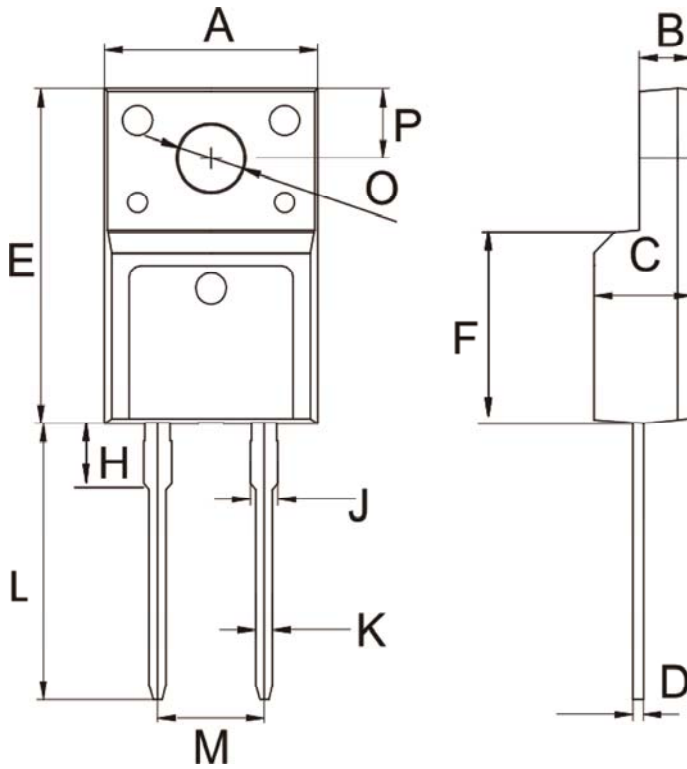
NCD8A65F

SILICON CARBIDE SCHOTTKY DIODE



OUTLINE DRAWINGS

TO-220F-2L



OUTLINE DIMENSIONS						
Dim.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.25	-	10.75	0.36	-	0.42
B	2.25	-	2.75	0.09	-	0.11
C	4.40	-	5.00	0.17	-	0.20
D	0.45	-	0.75	0.02	-	0.03
E	15.00	-	17.00	0.59	-	0.67
F	7.95	-	9.45	0.31	-	0.37
L	12.50	-	14.50	0.49	-	0.57
H	2.30	-	2.90	0.09	-	0.11
J	1.15	-	1.65	0.05	-	0.06
K	0.70	-	1.00	0.03	-	0.04
M	4.80	-	5.40	0.19	-	0.21
O	2.90	-	3.40	0.11	-	0.13
P	3.00	-	3.50	0.12	-	0.14

PACKING INFORMATION

Package Code	Package Method	Inner Box Size L×W×H(mm)	Quantity (Pcs/Inner Box)	Outer Carton Size L×W×H(mm)	Quantity (Pcs/Carton)
TO-220F-2L	T/P	560x155x55	1000	570×284×185	5000

NCD8A65F

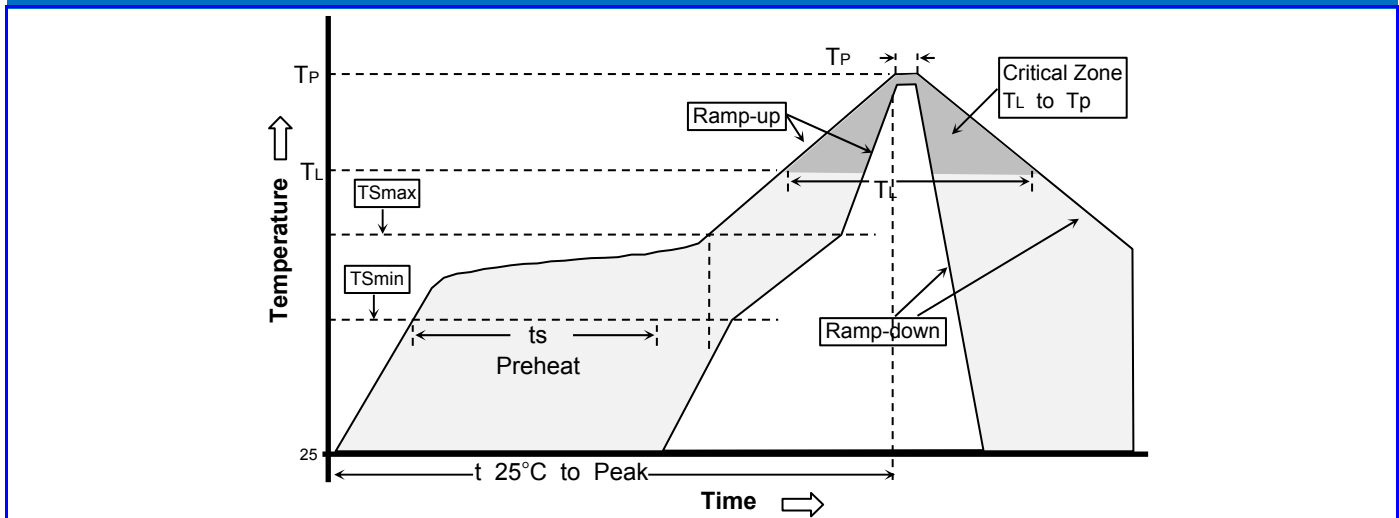
SILICON CARBIDE SCHOTTKY DIODE



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(T _S min) -Temperature Max(T _S max) -Time(t _s min to t _s max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (T _L) - Time (t _L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(t _p)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.



NCD8A65F

SILICON CARBIDE SCHOTTKY DIODE



Disclaimer

- Reproducing and modifying information of the document is prohibited without permission from Niuhan Electronics Co., Ltd.
- Niuhan Electronics Co., Ltd. reserves the rights to make changes of the content herein the document anytime without notification.
- Niuhan Electronics Co., Ltd. disclaims any and all liability arising out of the application or use of any product including damages incidentally and consequentially occurred.
- Niuhan Electronics Co., Ltd. does not assume any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.
- Applications shown on the herein document are examples of standard use and operation. Customers are responsible in comprehending the suitable use in particular applications. Niuhan Electronics Co., Ltd. makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.
- The products shown herein are not designed and authorized for equipments requiring high level of reliability or relating to human life and for any applications concerning life-saving or life-sustaining, such as medical instruments, transportation equipment, aerospace machinery et cetera. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Niuhan Electronics Co., Ltd. for any damages resulting from such improper use or sale.
- When the appearance of the product and chip size does not change, in order to product the customer quality, change the internal structure and the production process Niuhan can not notify